



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

The rev A is being issued to remove duplicate devices and add affected devices.

Notification Number:	20260914000.0A	Notification Issued	September 21, 2026
AMC03xx vSense Amplifiers Design Change			

Change Type(s)	Design
ZVEI ID	SEM-DE-01

Notification Details

Description of Change:							
Texas Instruments Incorporated is announcing an information only notification for the AMC03xx vSense Amplifiers die update. A die revision update as a result of the design change. Die Rev: <table><tr><td>Current</td><td>New</td></tr><tr><td>Die Rev [2P]</td><td>Die Rev [2P]</td></tr><tr><td>C</td><td>D</td></tr></table>		Current	New	Die Rev [2P]	Die Rev [2P]	C	D
Current	New						
Die Rev [2P]	Die Rev [2P]						
C	D						
Reason for Change:	Change to improve yield in the ATE test for noise outliers at cold temperatures.						
Anticipated impact on Form, Fit, Function, Quality or Reliability:	These devices include new die with schematic or behavior changes. No change to form or fit. No change to the datasheet parameters.						
Changes to product identification resulting from this PCN:	Sample product shipping label (not actual product label): 						

Products Affected:			
AMC0211DDR	AMC0311DDWVR	AMC0330SDWVR	AMC0381D10DFXR
AMC0211DQDRQ1	AMC0330SDWVR	AMC0330SQDWVRQ 1	AMC0381D10QDFXRQ 1
AMC0211RDR	AMC0311DQDWVR Q1	AMC0380D04DFXR	AMC0381D16DFXR
AMC0211RQDRQ1	AMC0311RDWVR	AMC0380D04QDFXR Q1	AMC0381D16QDFXRQ 1
AMC0211SDR	AMC0311RQDWVR Q1	AMC0380D06DFXR	AMC0381R06DFXR
AMC0211SQDRQ1	AMC0311SDWVR	AMC0380D06QDFXR Q1	AMC0381R06QDFXRQ 1

AMC0230DDR	AMC0211DDR	AMC0380R04DFXR	AMC0381R10DFXR
AMC0230DQDRQ1	AMC0311SQDWVR Q1	AMC0380R04QDFXR Q1	AMC0381R10QDFXRQ 1
AMC0230RDR	AMC0330DDWVR	AMC0380R06DFXR	AMC0381R16DFXR
AMC0230RQDRQ1	AMC0330DQDWVR Q1	AMC0380R06QDFXR Q1	AMC0381R16QDFXRQ 1
AMC0230SDR	AMC0330RDWVR	AMC0381D06DFXR	AMC0311DDWVR
AMC0230SQDRQ1	AMC0330RQDWVR Q1	AMC0381D06QDFXR Q1	

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

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